501988161 07/13/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takeshi HAMADA	04/26/2012
Yoshihiko KOIZUMI	04/26/2012

RECEIVING PARTY DATA

Name:	Asahi Kasei Microdevices Corporation	
Street Address:	1-105, Kanda Jinbocho, Chiyoda-ku,	
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State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13522114

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ATTORNEY DOCKET NUMBER: 100116-5024

NAME OF SUBMITTER: Mary Jane Boswell

Total Attachments: 1

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PATENT REEL: 028545 FRAME: 0141 ICH \$40.00 135221

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ATTORNEY DOCKET NO.: SOLE/JOINT INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

CHARGE PUMP CIRCUIT, CONTROL METHOD THEREOF, AND SEMICONDUCTOR INTEGRATED CIRCUIT

for which I/WE executed an application for Un application for United States Letters Patent on					
WHEREAS, ASAHI KASEI MICRODEVICES CORPORATION, a corporation of JAPAN, whose post office address is 1-105, Kanda Jinbocho, Chiyoda-ku, Tokyo, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;					
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;					
AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.					
AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. 13/522,114 , filed July 13, 2012) the filing date and application number of said application when known. IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).					
Full Name of Sole or First Assignor Takeshi HAMADA	Assignor's Signature Takeshi Hamada	Date 26.4.2012			
Address 1-105, Kanda Jinbocho, Chiyoda-ku, Tokyo 101-8101, Japan		Citizenship Japanese			
	Assignor's Signature	Date 26, 4. 2012			
Yoshihiko KOIZUMI (ວຣກົນໄຊດ Κοίζων) (Address 1-105, Kanda Jinbocho, Chiyoda-ku, Tokyo 101-8101, Japan		Citizenship Japanese			
Names of additional inventors attached Yes	⊠ No				
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PATENT REEL: 028545 FRAME: 0142